## B.Tech. - VIEP - ELECTRONICS AND COMMUNICATION ENGINEERING (BTECVI)

00726

## Term-End Examination June, 2015

**BIELE-007: NANO-ELECTRONICS** 

BIELE-UU7: NANU-ELECTRUNICS						
Time : 3 hours Maximum Marks						
Vo	<b>Note:</b> Attempt any <b>seven</b> questions. All questions carrequal marks.					
1.	(a)	What are the various interconnect issues for nano-scale MOSFET technology?	5			
	(b)	Explain 'hot-electron effect', in sub-micron technology.	5			
2.	(a)	What is nano-lithography? Discuss the difficulties associated with practical implementation of nano-lithography.	5			
	(b)	Explain the phenomenon of velocity saturation in MOSFETs.	5			
3.	(a)	What are the various scaling issues in nano-technology MOSFETs?	5			
	(b)	How is silicon-on-insulator technology different from silicon-on-nothing technology?	5			
BIELE-007 1			.O.			

4.	Disci	uss the similarities and dissimilarities in ET and multi-gate MOSFET.	10
5.	Write	e short notes on any $two$ of the wing: $2 \times 5$	=10
	(a)	Coulomb-Staircase	
	(b)	Vertical MOSFETs	
	(c)	Multiple gate MOSFETs	
6.	(a)	What do you understand by quantum well, quantum wire and quantum dot? Give an example of each.	5
	(b)	What are the distinctive features of resonant tunneling in diodes?	5
7.		y and explain the heterostructures of III-V II-VI compounds with their energy band cams.	10
8.	(a)	Explain the working of single electron devices with necessary diagrams.	5
	(b)	What are the different applications of resonant-tunneling devices? What are the	
		advantages of RTDs?	5

9.	Expla	ain Carbon Nano-tube Field Effect	
		sistor (CNFET). Derive the expression for	10
	tneor	etical value of drain current for CNFET.	. 10
10.	(a)	What are the main features of SpinFET?	
		Draw and explain the I-V characteristics of	
		SpinFET.	5
	(b)	Explain the various steps of fabrication for	
		SpinFET.	5